

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

VSMB2948SL is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic package (with lens) for surface mounting (SMD).

APPLICATIONS

- IR touch panels

FEATURES

Package type: surface mount

• Package form: side view



Peak wavelength: λ_p = 940 nm

· High reliability

· High radiant power

· High radiant intensity

• Angle of half intensity: $\varphi = \pm 25^{\circ}$

· Low forward voltage

• Suitable for high pulse current operation

• Package matches with detector VEMD2023SLX01 and VEMT2023SLX01

• Floor life: 4 weeks, MSL 2a, acc. J-STD-020

• Material categorization: For definitions of compliance please see www.vishay.com/doc?99912





<u>(5-2008)</u>

· Remote control

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)	
VSMB2948SL	20	± 25	940	15	

Note

· Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMB2948SL	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view	

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I _F	100	mA
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA
Power dissipation		P _V	160	mW
Junction temperature		T _j	100	°C
Operating temperature range		T _{amb}	- 40 to + 85	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	according figure 9, J-STD-020	T _{sd}	260	°C
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R _{thJA}	250	K/W



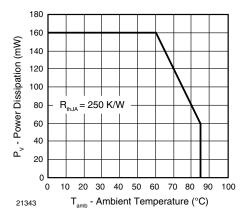


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

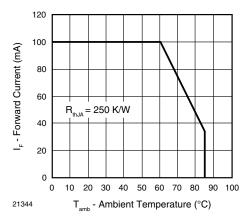


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	V_{F}	1.15	1.35	1.6	V
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	V_{F}		1.8		V
Temperature coefficient of V _F	I _F = 1 mA	TK _{VF}		- 1.5		mV/K
Reverse current	V _R = 5 V	I _R			10	μA
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ		21		pF
Radiant intensity	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	l _e	10	20	30	mW/sr
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	l _e		90		mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	фe		40		mW
Temperature coefficient of radiant power	I _F = 1 mA	TKφ _e		- 1.1		%/K
Angle of half intensity		φ		± 25		deg
Peak wavelength	I _F = 30 mA	λρ	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ		25		nm
Temperature coefficient of λ_p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		15		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		15		ns
Cut-off frequency	I _{DC} = 70 mA, I _{AC} = 30 mA pp	f _c		23		MHz

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

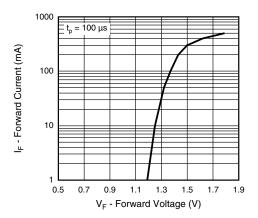


Fig. 3 - Forward Current vs. Forward Voltage

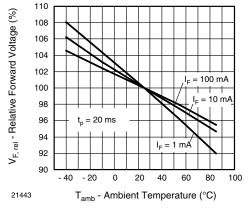


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

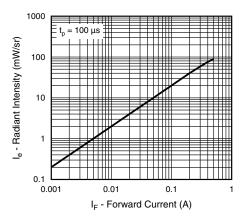


Fig. 5 - Radiant Intensity vs. Forward Current

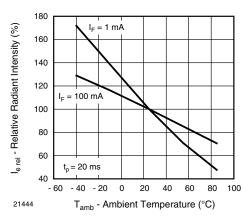


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

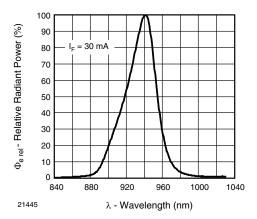


Fig. 7 - Relative Radiant Power vs. Wavelength

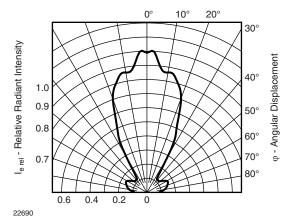


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



SOLDER PROFILE

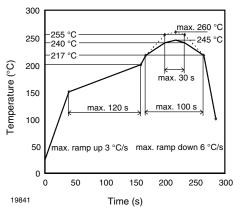


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

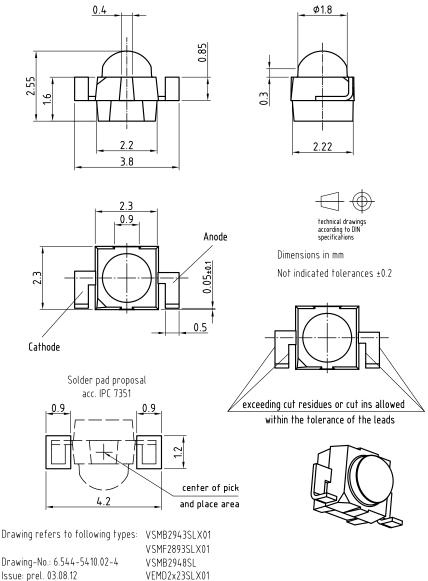
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

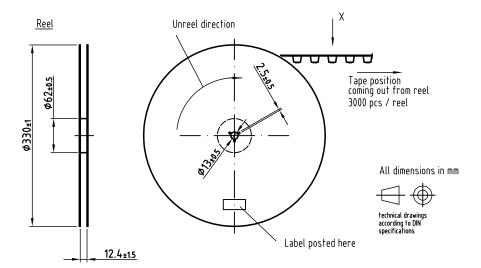
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ K.

PACKAGE DIMENSIONS in millimeters: VSMB2948SL

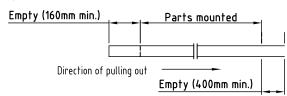




TAPING AND REEL DIMENSIONS in millimeters: VSMB2948SL

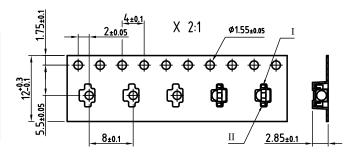


Leader and trailer tape:



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Lead I	Lead II
c 11 1	
Larnode	Anode
C. II	F-111
Collector	Emitter
Anode	Cathode
	Cathode Collector Anode



Drawing refers to following types: see table Reel dimensions and tape

Drawing-No.: 9.800-5123.01-4 Issue: prel; 01.02.13



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